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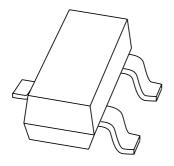
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DISCRETE SEMICONDUCTORS

# DATA SHEET



# **BAT17**Schottky barrier diode

Product data sheet Supersedes data of 1999 May 26 2003 Mar 25



# Schottky barrier diode

**BAT17** 

#### **FEATURES**

- Low forward voltage
- Small SMD package
- Low capacitance.

#### **APPLICATIONS**

- UHF mixer
- · Sampling circuits
- Modulators
- Phase detection.

#### **DESCRIPTION**

Planar Schottky barrier diode in a small SOT23 plastic SMD package.

#### **MARKING**

TYPE NUMBER	MARKING CODE <sup>(1)</sup>	
BAT17	A3*	

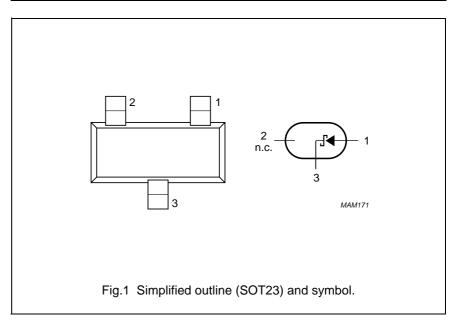
#### Note

\* = p : Made in Hong Kong.
\* = t : Made in Malaysia.

\* = W : Made in China.

#### **PINNING**

PIN	DESCRIPTION	
1	anode	
2	not connected	
3	cathode	



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER		MAX.	UNIT
$V_R$	continuous reverse voltage	_	4	V
I <sub>F</sub>	continuous forward current	_	30	mA
T <sub>stg</sub>	storage temperature	-65	+150	°C
Tj	junction temperature	_	100	°C

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#### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage see Fig.2			
		I <sub>F</sub> = 0.1 mA	350	mV
		I <sub>F</sub> = 1 mA	450	mV
		I <sub>F</sub> = 10 mA	600	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 3 V; see Fig.3	0.25	μΑ
		$V_R = 3 \text{ V}; T_{amb} = 60 ^{\circ}\text{C}; \text{ see Fig.3}$	1.25	μΑ
$r_D$	diode forward resistance	$f = 1 \text{ kHz}; I_F = 5 \text{ mA}$	15	Ω
C <sub>d</sub>	diode capacitance	$f = 1 \text{ MHz}$ ; $V_R = 0$ ; see Fig.4	1	pF
F	noise figure	f = 900 MHz; note 1 8 dB		dB

#### Note

1. The local oscillator is adjusted for a diode current of 2 mA. IF amplifier noise  $F_{if}$  = 1.5 dB; f = 35 MHz.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

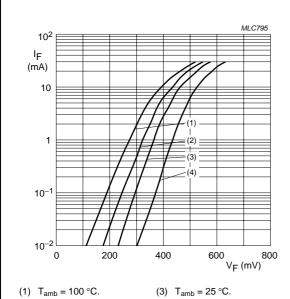
1. Refer to SOT23 standard mounting conditions.

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# Schottky barrier diode

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#### **GRAPHICAL DATA**



- (3)  $T_{amb} = 25 \,^{\circ}C$ .
- (2)  $T_{amb} = 60 \, ^{\circ}C$ . (4)  $T_{amb} = -40 \, ^{\circ}C$ .

Fig.2 Forward current as a function of forward voltage; typical values.

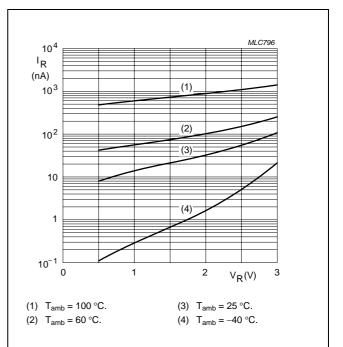
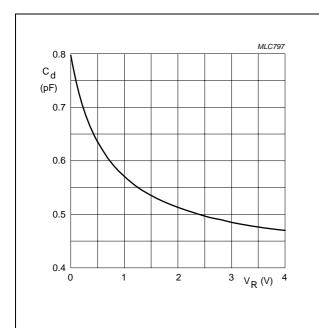


Fig.3 Reverse current as a function of reverse voltage; typical values.



f = 1 MHz;  $T_{amb} = 25 \,^{\circ}\text{C}$ .

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

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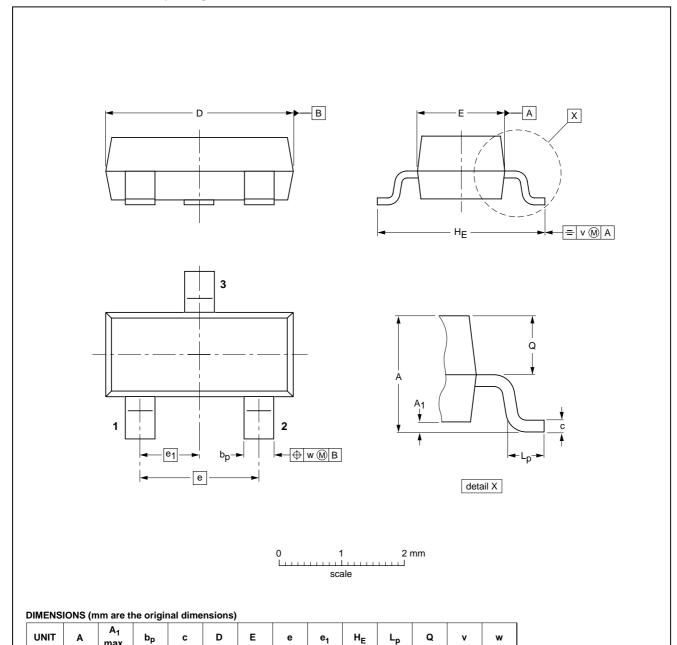
# Schottky barrier diode

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#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

SOT23



OUTLINE		REFERENCES			EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>97-02-28</del> 99-09-13

0.95

0.45

0.15

0.55

0.45

0.1

1.4 1.2

1.9

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0.48

0.38

0.1

mm

0.15

0.09

3.0

2.8

### Schottky barrier diode

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#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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## **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors. No changes were made to the content, except for the legal definitions and disclaimers.

#### **Contact information**

For additional information please visit: http://www.nxp.com

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